

#### **Product Features**

- High dynamic range downconverter with integrated LO, IF, & RF amps
- RF: 1900 2200 MHz
- IF: 65 300 MHz
- +38 dBm Output IP3
- +21 dBm Output P1dB
- 5.3 dB Noise Figure
- +5V Single supply operation
- Pb-free 6mm 28-pin QFN package
- · Low-side LO configuration
- Common footprint with other PCS/ cellular versions

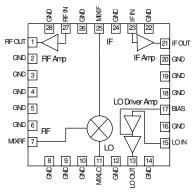
# **Product Description**

The CV111-3A is a high linearity downconverter designed to meet the demanding issues for performance, functionality, and cost goals of current and next generation mobile infrastructure basestations. It provides high dynamic range performance in a low profile surface-mount leadless package that measures 6 x 6 mm square.

Functionality includes RF amplification, frequency conversion and IF amplification, while an integrated LO driver amplifier powers the passive mixer. The MCM is implemented with reliable and mature GaAs MESFET and InGaP HBT technology.

Typical applications include frequency down conversion, modulation and demodulation for receivers used in CDMA, CDMA2000, W-CDMA / IMT2000, GPRS, and EDGE 2.5G mobile infrastructure technologies for UMTS frequency bands.

## **Functional Diagram**



Top View

# Specifications (1)

| Parameters                             | Units            | Min  | Тур         | Max  | Comments                        |
|--|------------------|------|-------------|------|---------------------------------|
| RF Frequency Range                     | MHz              |      | 1900 – 2200 |      |                                 |
| LO Frequency Range                     | MHz              |      | 1600 - 2135 |      |                                 |
| IF Center Frequency Range              | MHz              |      | 65 - 300    |      | See note 2                      |
| % Bandwidth around IF center frequency | %                |      | ±7.5        |      | See note 3                      |
| IF Test Frequency                      | MHz              |      | 75          |      |                                 |
| SSB Conversion Gain                    | dB               |      | 21.5        |      | Temp = $25$ °C                  |
| Gain Drift over Temp (-40 to 85 °C)    | dB               |      | ±0.5        |      | Referenced to +25 °C            |
| Output IP3                             | dBm              |      | +38         |      | See note 4                      |
| Output IP2                             | dBm              |      | +48         |      | See note 4                      |
| Output 1dB Compression Point           | dBm              |      | +21         |      |                                 |
| Noise Figure                           | dB               |      | 5.3         |      | See note 5                      |
| LO Input Drive Level                   | dBm              | -2.5 | 0           | +2.5 |                                 |
| LO-RF Isolation                        | dB               |      | 40          |      | $P_{LO} = 0 \text{ dBm}$        |
| LO-IF Isolation                        | dB               |      | 25          |      | $P_{LO} = 0 \text{ dBm}$        |
| Return Loss: RF Port                   | dB               |      | 14          |      |                                 |
| Return Loss: LO Port                   | dB               |      | 14          |      |                                 |
| Return Loss: IF Port                   | dB               |      | 14          |      |                                 |
| Operating Supply Voltage               | V                | +4.9 | +5          | +5.1 |                                 |
| Supply Current                         | mA               | 290  | 360         | 480  |                                 |
| FIT Rating                             | failures/1E9 hrs |      |             | 72.1 | @ 70° C ambient, 90% confidence |
| Junction Temperature                   | °C               |      |             | 160  | See note 6                      |

# **Absolute Maximum Rating**

| Parameter                  | Rating         |
|----------------------------|----------------|
| Operating Case Temperature | -40 to +85° C  |
| Storage Temperature        | -55 to +125° C |
| DC Voltage                 | +6 V           |
| Junction Temperature       | +220 °C        |
| RF Input (continuous)      | +2 dBm         |

# **Ordering Information**

| Part No.       | Description   |
|----------------|---|
| CV111-3AF      | UMTS-band High Linearity Downconverter (lead-free/RoHS-compliant QFN Pkg) |
| CV111-3APCB75  | Fully Assembled Eval. Board, IF = 75MHz                                   |
| CV111-3APCB240 | Fully Assembled Eval. Board, IF = 240MHz                                  |

Operation of this device above any of these parameters may cause permanent damage.

Specifications and information are subject to change without notice

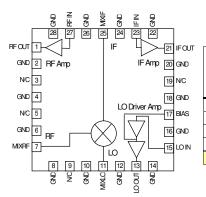
Specifications when using the application specific circuit (shown on page 3) with a low side LO = 0 dBm in a downconverting application over the operating case temperature range. IF matching components affect the center IF frequency. Proper component values for other IF center frequencies than shown can be provided by emailing to applications.engineering@wj.com. The IF bandwidth of the converter is defined as 15% around any center frequency in its operating IF frequency range. The bandwidth is determined with external components. Specifications are valid around the total ±7.5% bandwidth. ie. with a center frequency of 80 MHz, the specifications are valid from 80 ± 6 MHz.

Assumes the supply voltage = +5 V. OIP3 is measured with  $\Delta f = 1$  MHz with  $\Gamma_{OUT} = 5$  dBm/tone.

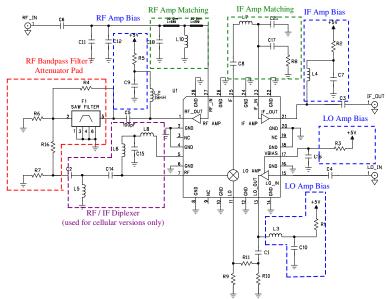
Assumes LO injection noise is filtered at the thermal noise floor, -174 dBm/Hz, at the RF, IF, and Image frequencies.

The maximum junction temperature ensures a minimum MTTF rating of 1 million hours of usage.

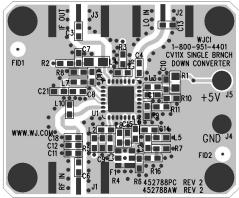
# **Device Architecture / Application Circuit Information**



| Typical Downconverter Performance Chain Analysis |                             |               |              |            |              |                        |                         |                        |            |
|--|-----------------------------|---------------|--------------|------------|--------------|------------------------|-------------------------|------------------------|------------|
|  |                             | Output        | Output       |            |              | Cumulative Performance |                         |                        |            |
| Stage  | Gain<br>(dB)                | P1dB<br>(dBm) | IP3<br>(dBm) | NF<br>(dB) | Current (mA) | Gain (dB)              | Output<br>P1dB<br>(dBm) | Output<br>IP3<br>(dBm) | NF<br>(dB) |
| RF Amplifier                                     | 13                          | 21            | 41           | 3.5        | 140          | 13                     | 21.0                    | 41.0                   | 3.5        |
| RF Filter  | -2                          |               |              | 2.0        |              | 11                     | 19.0                    | 39.0                   | 3.6        |
| LO Amp / MMIC Mixer                              | -8.5                        | 8             | 23           | 9.3        | 80           | 2                      | 5.9                     | 22.2                   | 4.7        |
| IF Amplifier                                     | 19                          | 23            | 41           | 2.1        | 140          | 21                     | 20.8                    | 38.1                   | 5.2        |
| CV111-3A   | 1-3A Cumulative Performance |               | 360          | 21.0       | 20.8         | 38.1                   | 5.2                     |                        |            |



Printed Circuit Board Material: .014" FR-4, 4 layers, .062" total thickness



CV111-3A: The application circuit can be broken up into four main functions as denoted in the colored dotted areas above: RF/IF diplexing (purple; this is only used with the cellular-band CV products), amplifier matching (green), filtering (red), and dc biasing (blue). There are various placeholders for chip components in the circuit schematic so that a common PCB can be used for all WJ single-branch converters. Additional placeholders for other optional functions such as filtering are also included.

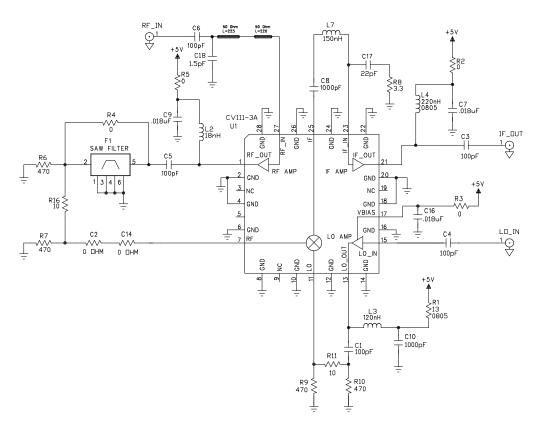
RF / IF Amplifier Matching: The RF amplifier requires a shunt matching element for optimal gain and input return loss performance. The IF amplifier requires matching elements to optimize the performance of the amplifier to the desired IF center frequency. Since IF bandwidths are typically on the order of 5 to 10%, a simple two element matching network, in the form of either a high-pass or low-pass filter structure, is sufficient to match the MMIC IF amplifier over these narrow bandwidths. Proper component values for other IF center frequencies can be provided by emailing to applications.engineering@wj.com.

**RF Bandpass Filtering:** Bandpass filtering is recommended to achieve the best noise figure performance with the downconverter. The bandpass filter, implemented with a SAW filter on the application circuit, allows for the suppression of noise from the image frequency. It is permissible to not use a filter and use a 2 dB pad with R6, R7, and R16 instead with slightly degraded noise figure performance.

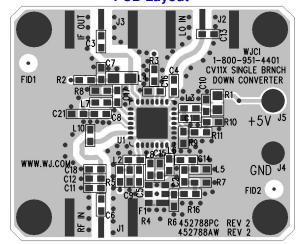
**External Diplexer:** This is only used with the cellular-band CV products. The mixer performs the diplexing internally for the CV111-3A; therefore the components shown in the diplexer section should be loaded as follows:  $C2 = C14 = 0 \Omega$ .

**DC** biasing: DC bias must be provided for the RF, LO and IF amplifiers in the converter. R1 sets the operating current for the last stage of the LO amplifier and is chosen to optimize the mixer LO drive level. Proper RF chokes and bypass capacitors are chosen for proper amplifier biasing at the intended frequency of operation. The "+5 V" dc bias should be supplied directly from a voltage regulator.

# **Downconverting Application Circuit: CV111-3APCB75**RF = 1900 - 2200 MHz, IF = 75 MHz



#### **PCB Layout**



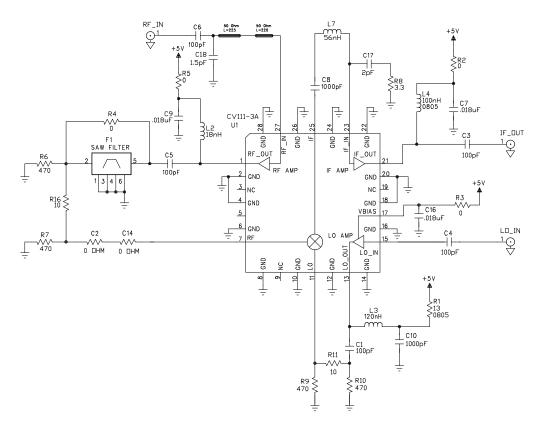
Circuit Board Material: .014" FR-4, 4 layers, .062" total thickness

#### **Bill of Materials**

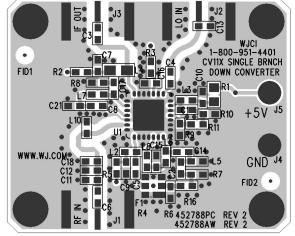
| Ref. Desig.  | Component  |
|--|--|
| R1   | 13 Ω chip resistor, size 0805                        |
| R2, R3, R4, R5,<br>C2, C14                         | 0 Ω chip resistor                                    |
| R6, R7, R9, R10                                    | 470 Ω chip resistor                                  |
| R8   | $3.3 \Omega$ chip resistor                           |
| R11, R16   | 10 Ω chip resistor                                   |
| C1, C3, C4, C5, C6                                 | 100 pF chip capacitor                                |
| C7, C9, C16  | 0.018 μF chip capacitor                              |
| C8, C10  | 1000 pF chip capacitor                               |
| C11, C12, C13, C15,<br>C21, F1, L5, L6, L8,<br>L10 | Shown in silkscreen, but not used in actual circuit. |
| C17  | 22 pF chip capacitor                                 |
| C18  | 1.5 pF chip capacitor                                |
| L2   | 18 nH chip inductor                                  |
| L3   | 120 nH chip inductor                                 |
| L4   | 220 nH chip inductor, size 0805                      |
| L7   | 22 nH chip inductor                                  |
| U1   | CV111-3A WJ Converter                                |

All components are of size 0603 unless otherwise specified.

# Downconverting Application Circuit: CV111-3APCB240 RF = 1900 - 2200 MHz, IF = 240 MHz



#### **PCB** Layout



Circuit Board Material: .014" FR-4, 4 layers, .062" total thickness

#### **Bill of Materials**

| Ref. Desig.  | Component  |
|--|--|
| R1   | 13 Ω chip resistor, size 0805                        |
| R2, R3, R4, R5,<br>C2, C14                         | 0 Ω chip resistor                                    |
| R6, R7, R9, R10                                    | 470 Ω chip resistor                                  |
| R8   | 3.3 $\Omega$ chip resistor                           |
| R11, R16   | 10 Ω chip resistor                                   |
| C1, C3, C4, C5, C6                                 | 100 pF chip capacitor                                |
| C7, C9, C16  | 0.018 μF chip capacitor                              |
| C8, C10  | 1000 pF chip capacitor                               |
| C11, C12, C13, C15,<br>C21, F1, L5, L6, L8,<br>L10 | Shown in silkscreen, but not used in actual circuit. |
| C17  | 2 pF chip capacitor                                  |
| C18  | 1.5 pF chip capacitor                                |
| L2   | 18 nH chip inductor                                  |
| L3   | 120 nH chip inductor                                 |
| L4   | 100 nH chip inductor, size 0805                      |
| L7   | 56 nH chip inductor                                  |
| U1   | CV111-3A WJ Converter                                |

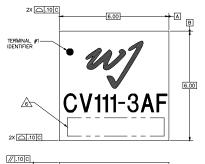
All components are of size 0603 unless otherwise specified.



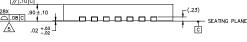
### CV111-3AF Mechanical Information

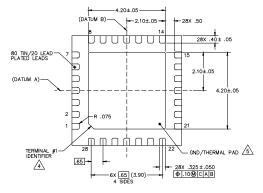
This package is lead-free/RoHS-compliant. It is compatible with both lead-free (maximum 260°C reflow temperature) and leaded (maximum 245°C reflow temperature) soldering processes. The plating material on the pins is annealed matte tin over copper.

# **Outline Drawing**

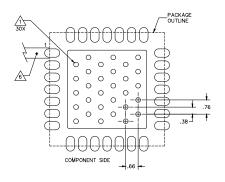


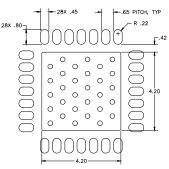
- TO JEDEC STANDARD MO-220, ISSUE E (VARIATIC VJJC) FOR THERMALLY ENHANCED PLASTIC VERY FINE PITCH QUAD FLAT NO LEAD PACKAGE (QFN).
- DIMENSIONING & TOLERANCING CONFORM TO ASME Y14.4M-1994.
- ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.
- COPLANARITY APPLIES TO THE EXPOSED GROUND/THERMAL PAD AS WELL AS THE TERMINALS.
- ALPHA-NUMERIC LOT CODE.

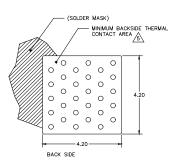




# **Mounting Configuration / Land Pattern**







#### NOTES:

- Λ GROUND/THERMAL MAS ARE CRITICAL FOR THE PROPER PERFORMANC OF THIS DEVICE. WAS SHOULD USE A .35mm (#80/.0135") DIAMETER DRILL AND HAVE A FINAL, PLATED THRU DIAMETER OF .25mm (.010").
- ADD AS MUCH COPPER AS POSSIBLE TO INNER AND OUTER LAYERS NEAR THE PART TO ENSURE OPTIMAL THERMAL PERFORMANCE.
- TO ENSURE RELIABLE OPERATION, DEVICE GROUND PADDLE-TO-GROUND PAD SOLDER JOINT IS CRITICAL.
- ADD MOUNTING SCREWS NEAR THE PART TO FASTEN THE BOARD TO A HEATSINK. ENSURE THAT THE GROUND/THERMAL VIA REGION CONTACTS THE HEATSINK
- DO NOT PUT SOLDER MASK ON THE BACK SIDE OF THE PC BOARD IN THE REGION WHERE THE BOARD CONTACTS THE HEATSINK.
- 6 RF TRACE WIDTH DEPENDS UPON THE PC BOARD MATERIAL AND CONSTRUCTION.
- USE 1 OZ. COPPER MINIMUM.
- ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.

# **Product Marking**

The component will be lasermarked with a "CV111-3AF" product label with alphanumeric lot code on the top surface of the package.

Tape and reel specifications for this part will be located on the website in the "Application Notes" section.

#### **ESD / MSL Information**



Caution! ESD sensitive device.

ESD Rating: Class 1B

Passes  $\geq 500V$  to <1000VValue: Human Body Model (HBM) Test: Standard: JEDEC Standard JESD22-A114

ESD Rating: Class III

Passes  $\geq 500V$  to <1000VValue: Test: Charged Device Model (CDM) Standard: JEDEC Standard JESD22-C101

MSL Rating: Level 2 at +260°C convection reflow JEDEC Standard J-STD-020 Standard:

# **Functional Pin Layout**

| Pin | Function       | Pin | Function        |
|-----|----------------|-----|-----------------|
| 1   | RF Amp Output  | 15  | LO Amp Input    |
| 2   | GND            | 16  | GND             |
| 3   | N/C or GND     | 17  | LO Amp Bias     |
| 4   | GND            | 18  | GND             |
| 5   | N/C or GND     | 19  | N/C or GND      |
| 6   | GND            | 20  | GND             |
| 7   | Mixer RF Input | 21  | IF Amp          |
| ,   |                |     | Output/Bias     |
| 8   | GND            | 22  | GND             |
| 9   | N/C or GND     | 23  | IF Amp Input    |
| 10  | GND            | 24  | GND             |
| 11  | Mixer LO Input | 25  | Mixer IF Output |
| 12  | GND            | 26  | GND             |
| 13  | LO Amp Output  | 27  | RF Amp Input    |
| 14  | GND            | 28  | GND             |